## Notice of References Cited

Application/Control No. 09/895,478

Applicant(s)/Patent Under Reexamination HARNDEN ET AL.

Examiner

Timothy J Sutton

Art Unit 2813

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## U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	Α	US-5,760,468	06-1998	King et al.	257/666
*	В	US-5,224,021	06-1993	Takada et al.	174/52.2
	С	US-6,297,546	10-2001	Moden, Walter L.	257/669
	D	US-5,227,995 /	07-1993	Klink et al.	257/666
	E	US-5,616,953	04-1997	King et al.	257/666
	F	US-			
	G	US-			
	Н	US-			
	ı	US-			
	J	US-			
	к	US-			
	L	US-			
	М	US-			

## FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	0				·	
	Р					
	Q					
	R					
	s					
	Т					

## NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	JEDEC Solid State Product Outline, "Low Profile Small Outline J-Lead Package (LSOJ), PRSO-J/LSOJ, Issue B, June 1999, MO-199, pp 1-5.
	٧	
	w	
	х	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)

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